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(54) Title: ULTRATHIN COMPOSITE DIELECTRICS FOR USE IN PRINTED CIRCUIT BOARDS

FIG. 1



(57) Abstract: Dielectric material layers including thermoplastic liquid crystal polymer (LCP) substrates coated or impregnated with a thermosetting resin. The dielectric material layers may have a dielectric constant (DK) value of less than about 3.4 and a dissipation factor of less than about 0.005 for use in printed circuit boards. The dielectric material layers may find particular utility in high density interconnect (HDI) printed circuit boards.



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